

# Compact Models for Transient Voltage

## Distributed RC Models

- ~~N-Line Solution~~
- ~~1-Line Solution~~
- **2-Line Example**



## Coupled Line Solutions

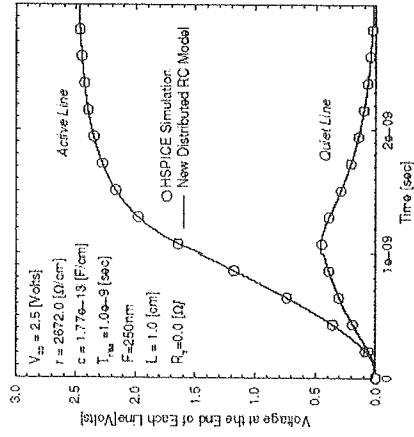
Region I:  $t \leq T_{rise}$

$$\frac{V_2}{V_{dd}} = \frac{C_m (R + 2R_s) + B_0^+ e^{-\frac{\sigma_0^+}{RC}t} - E_0^- e^{-\frac{\sigma_0^-}{RC}t}}{2T_{rise}}$$

Region II:  $t > T_{rise}$

$$\frac{V_2}{V_{dd}} = \frac{-E_0^- e^{-\frac{\sigma_0^-}{RC}t} (-e^{\frac{\sigma_0^-}{RC}T_{rise}} + 1) + B_0^+ e^{-\frac{\sigma_0^+}{RC}t} (1 - e^{\frac{\sigma_0^+}{RC}T_{rise}})}{2T_{rise}}$$

## HSPICE Comparison



## Peak Crosstalk Expression

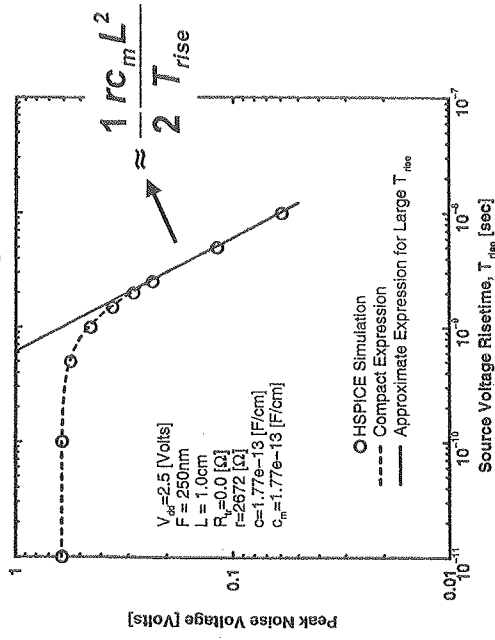
$$\frac{V_{peak}}{V_{dd}} = \frac{\chi B_0^+}{T_{rise}} \left( 1 - e^{\frac{\sigma_0^+ T_{rise}}{L^2 r c^+}} \right) \left( 1 - \frac{\sigma_0^+ c^-}{\sigma_0^- c^+} \right) \left( \frac{\sigma_0^+ c^- B_0^+}{\sigma_0^- c^+ B_0^-} \frac{1 - e^{\frac{T_{rise} \sigma_0^+}{L^2 r c^+}}}{1 - e^{\frac{T_{rise} \sigma_0^-}{L^2 r c^-}}} \right)$$

## Parameter Definitions

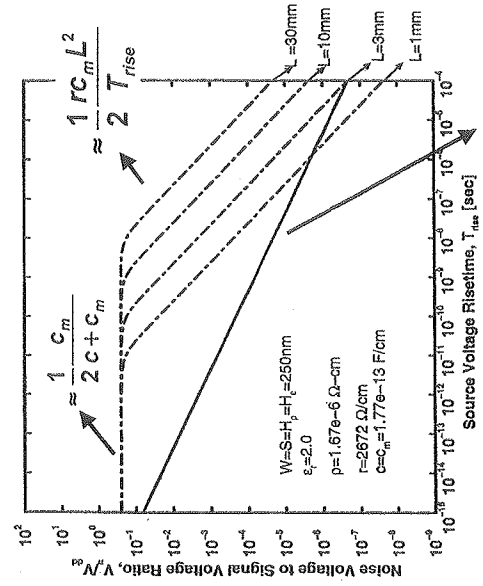
$$\sigma_o^\pm = \frac{1.04}{R_{tr} C_L + \frac{R_{tr}}{rL} + \frac{C_L}{c^\pm L} + \left(\frac{2}{\pi}\right)^2}$$

$$B_o^\pm = 1.01 \frac{r c^\pm L^2}{R_{tr} + \frac{C_L}{c^\pm L} + 1} \sigma_o^\pm \frac{C_L}{rL} + \frac{C_L}{c^\pm L} + \frac{\pi}{4}$$

## HSPICE Comparison



## Length Dependence



## Fundamental Thermal Noise Limit

## Sakurai's key RC result

$$\frac{V_{psk}}{V_d} \approx \frac{1}{2} \frac{c_m}{c + c_m}$$

Parallel plate Approximation

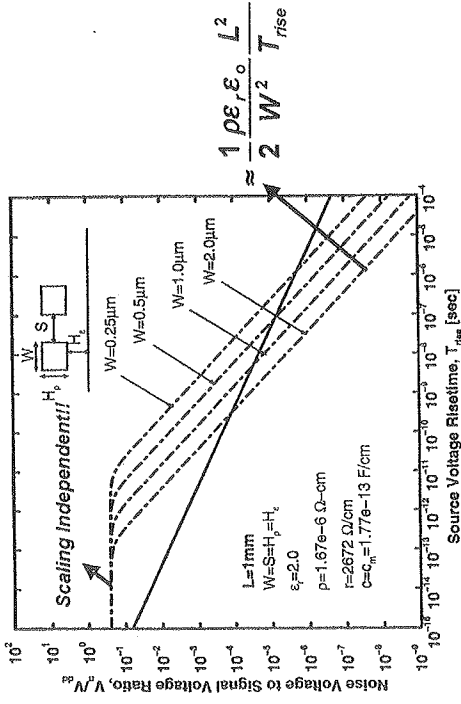
$$\frac{1}{2} \frac{W}{H_e} \frac{H_p}{S} + \frac{H_c}{S}$$

$$R_s = 0$$

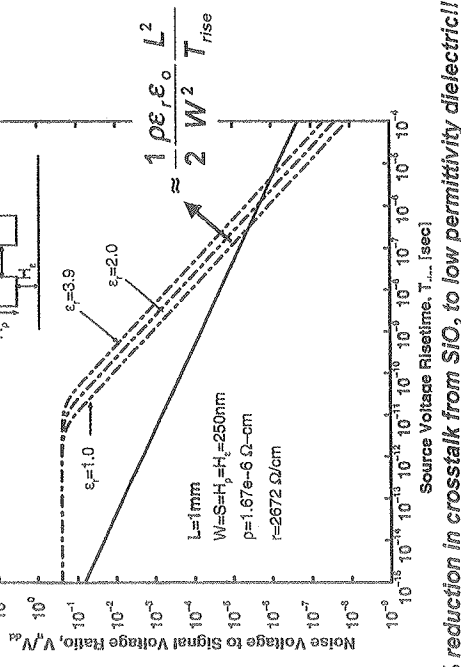
Approximately length, material, and scaling independents!!

What can we learn from  $T_{rise}$  expressions?

# Scaling Dependence

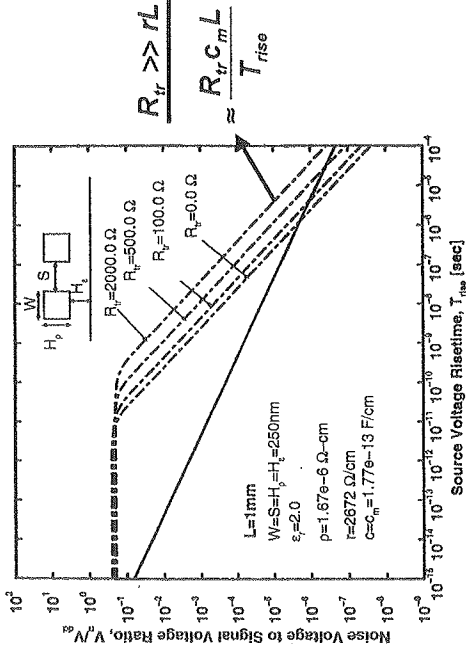


# Material Dependence



50% reduction in crosstalk from SiO<sub>2</sub> to low permittivity dielectric!!

# Driver Resistance Dependence

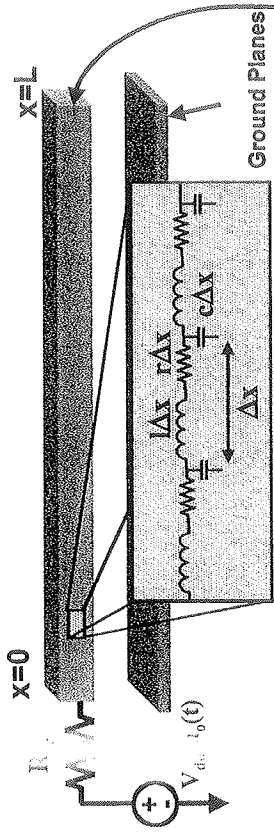


# Compact Models for Transient Voltage

## Distributed RLC Models

- ➔ N-Line Solution
- 1-Line Solution
- 2-Line Example

# Distributed RLC Model

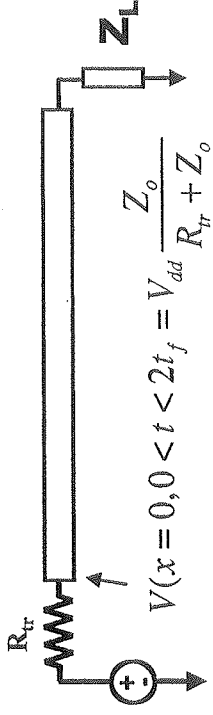


$$\frac{\partial^2}{\partial x^2} V(x,t) = rc \frac{\partial}{\partial t} V(x,t) + lc \frac{\partial^2}{\partial t^2} V(x,t)$$

Open Circuit Terminations

$$\left| \frac{1}{j\omega C_L} \right| \gg rL$$

# Review: Lossless Transmission Line Analysis



$$V(x=0, 0 < t < 2t_f) = V_{dd} \frac{Z_o}{R_{tr} + Z_o}$$

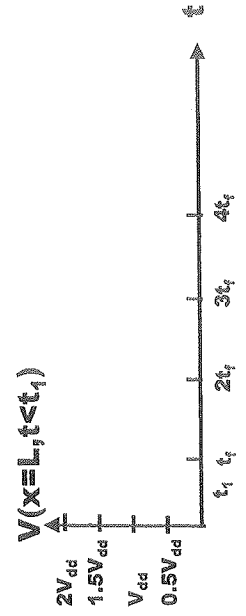
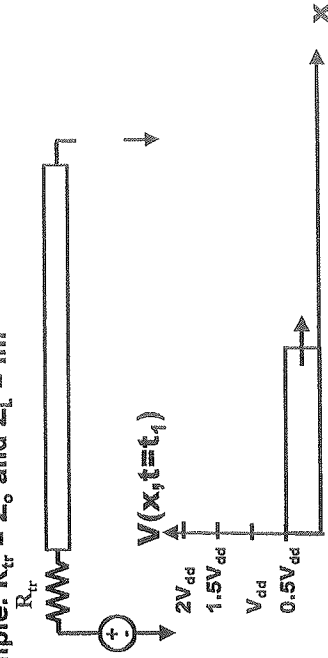
$$\Gamma_s = \frac{R_{tr} - Z_o}{R_{tr} + Z_o} \quad \Gamma_L = \frac{Z_L - Z_o}{Z_L + Z_o}$$

$$Z_o = \sqrt{\frac{l}{c}}$$

$$t_f = L/v = \sqrt{lc}L$$

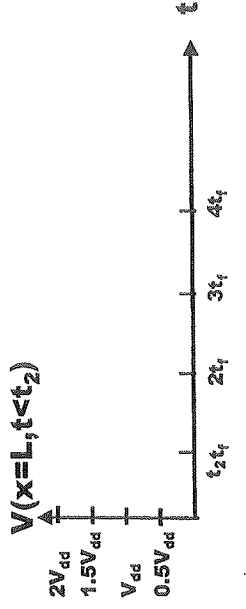
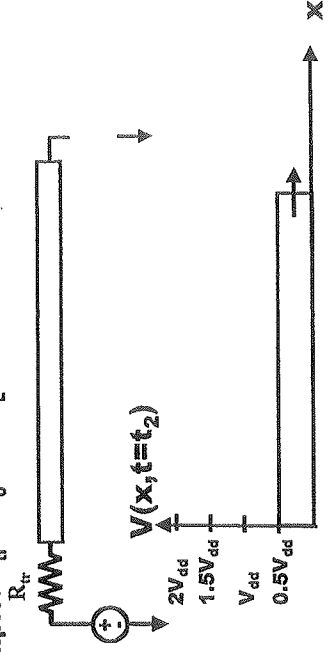
# Review: Lossless Transmission Line Analysis

Example:  $R_{tr} = Z_o$  and  $Z_L = \text{inf}$



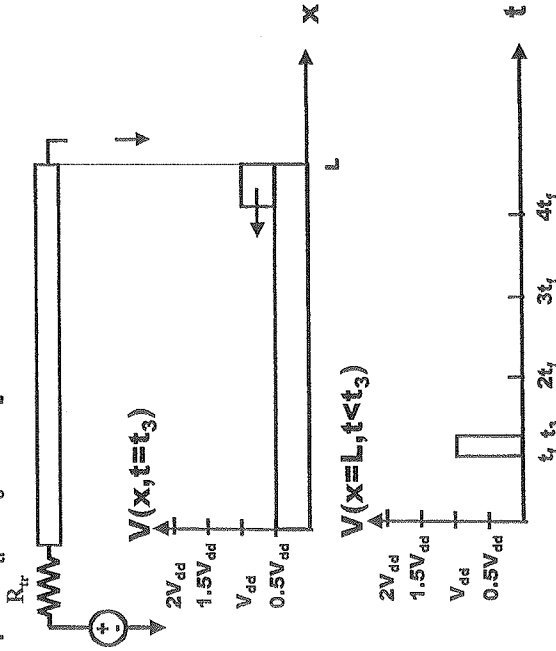
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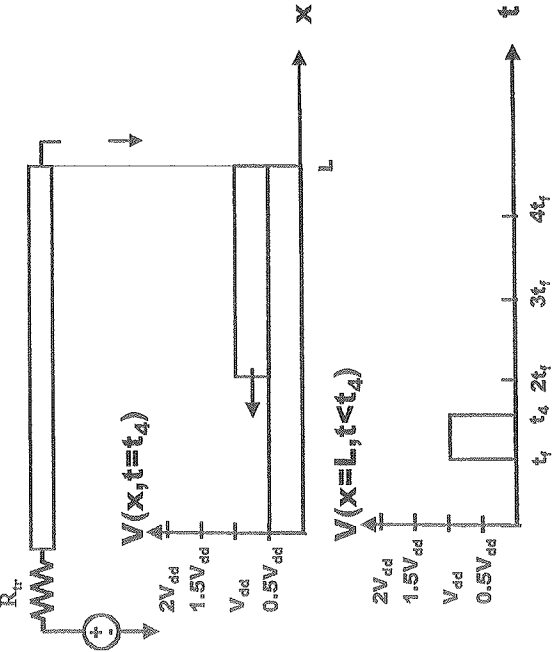
**Review: Lossless Transmission Line Analysis**

Example:  $R_{tr} = Z_0$  and  $Z_L = \text{inf}$



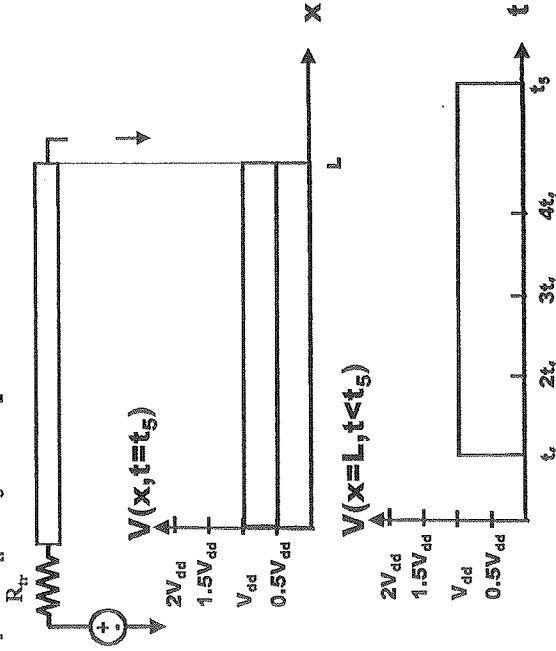
**Review: Lossless Transmission Line Analysis**

Example:  $R_{tr} = Z_0$  and  $Z_L = \text{inf}$



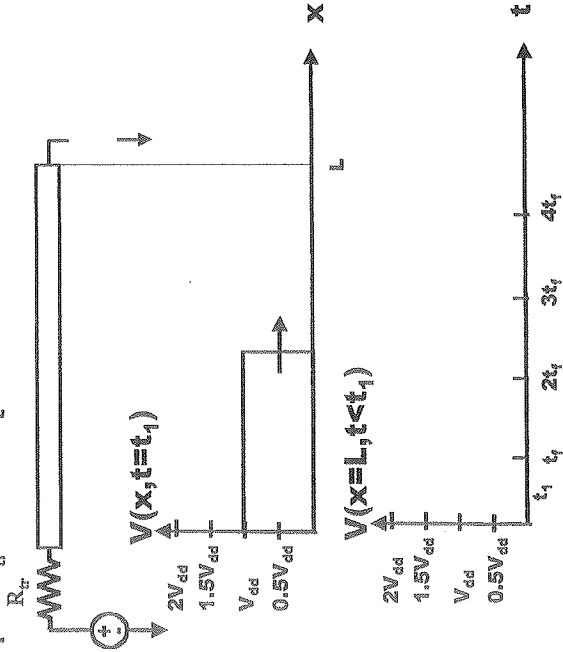
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Example:  $R_{tr} = Z_0$  and  $Z_L = \text{inf}$



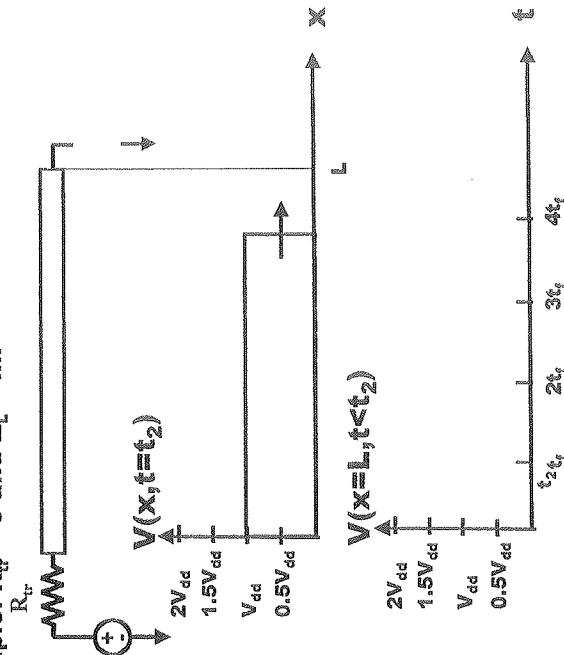
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Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



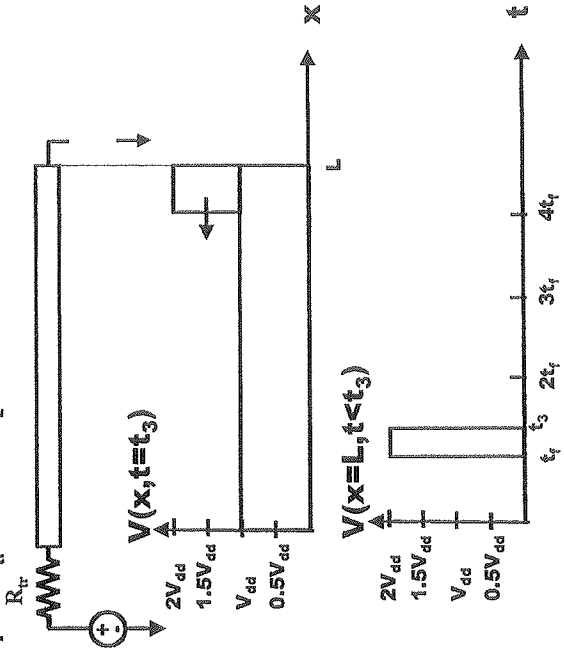
**Review: Lossless Transmission Line Analysis**

Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



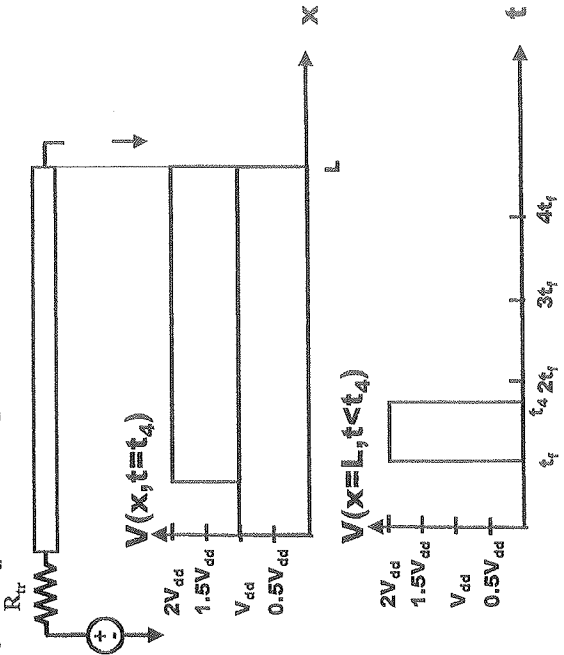
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Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



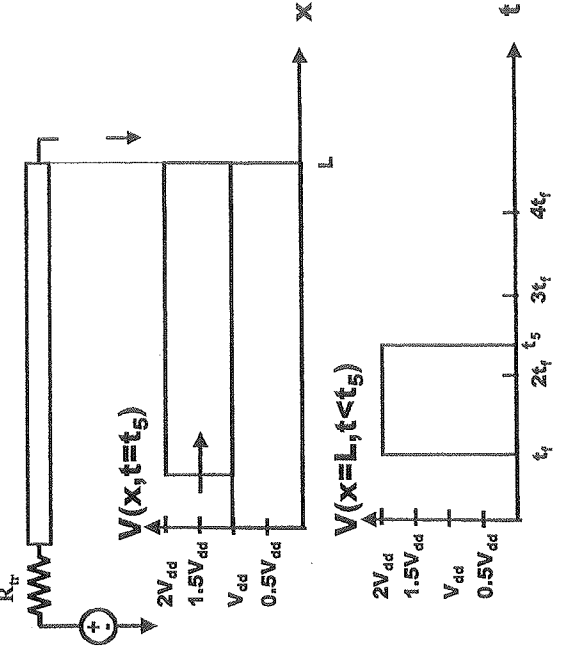
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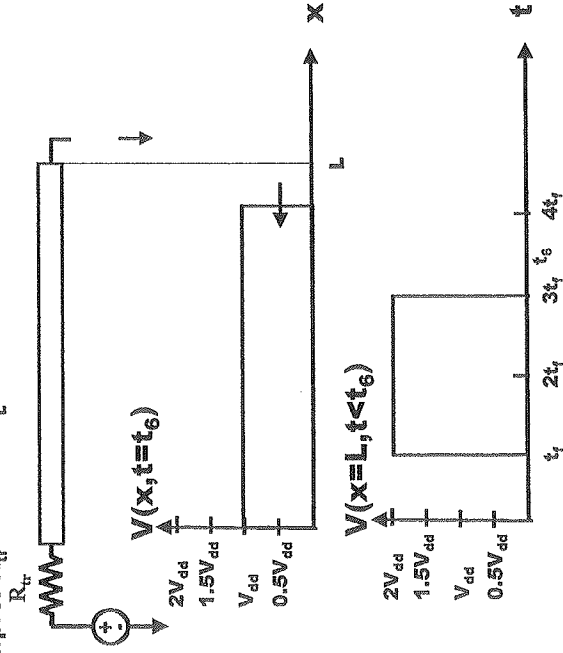
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Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



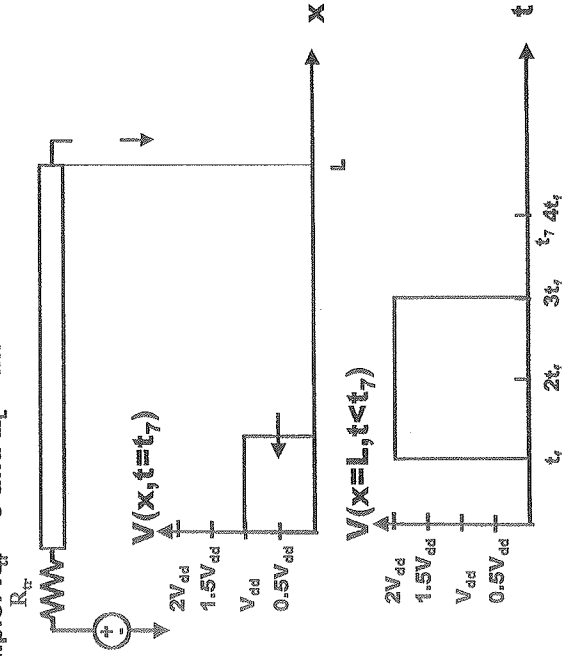
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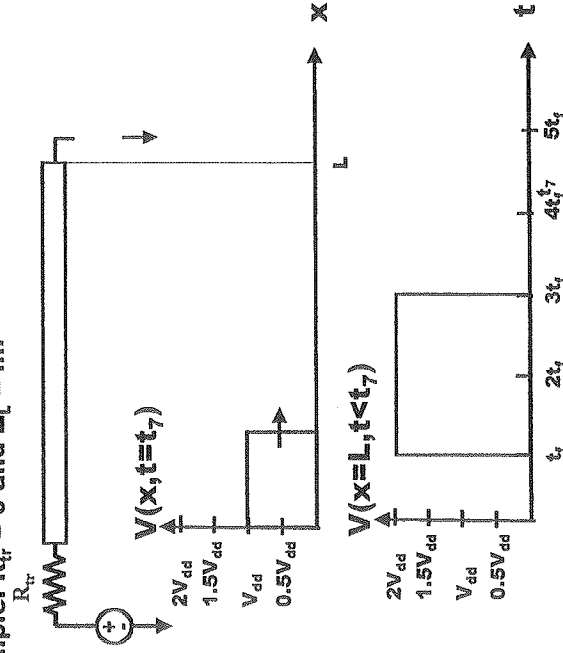
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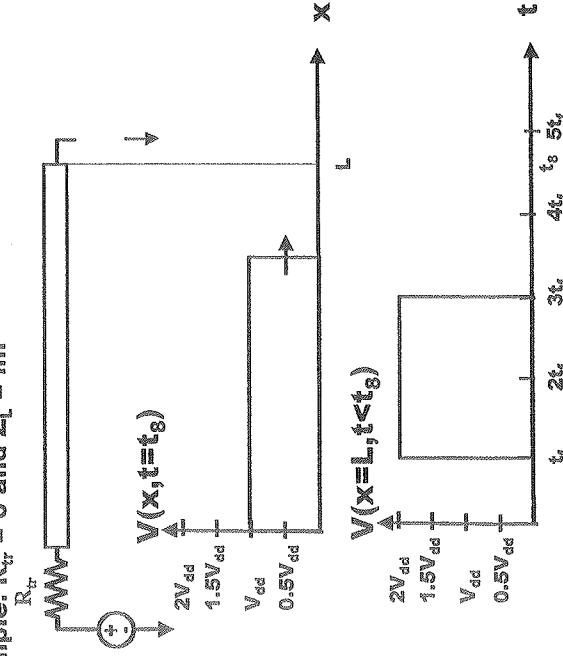
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Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



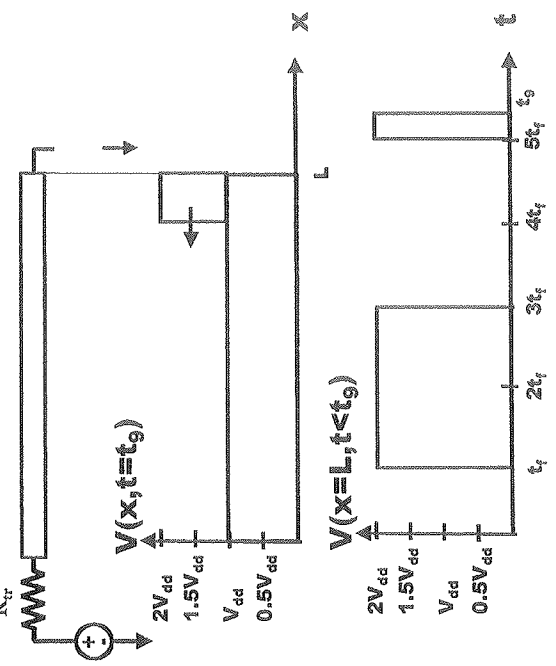
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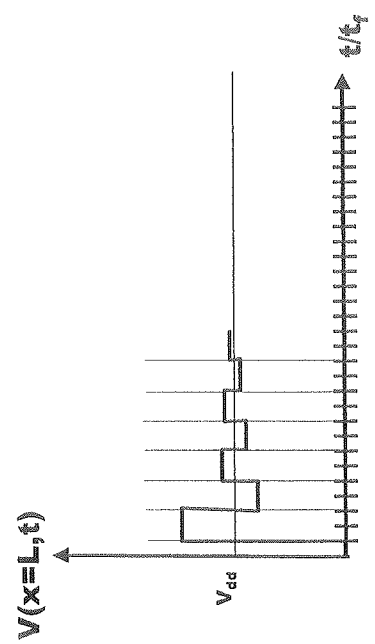
### Review: Lossless Transmission Line Analysis

Example:  $R_{tr} = 0$  and  $Z_L = \text{inf}$



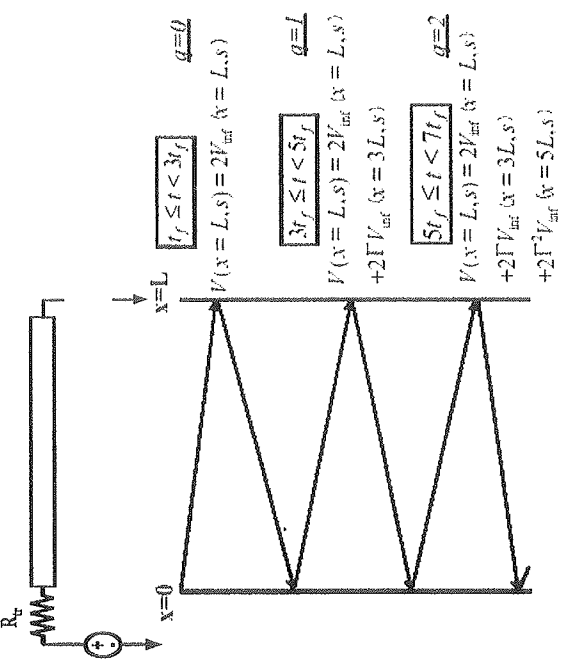
### Review: Lossless Transmission Line Analysis

Example:  $0 < R_{tr} < Z_0$  and  $Z_L = \text{inf}$



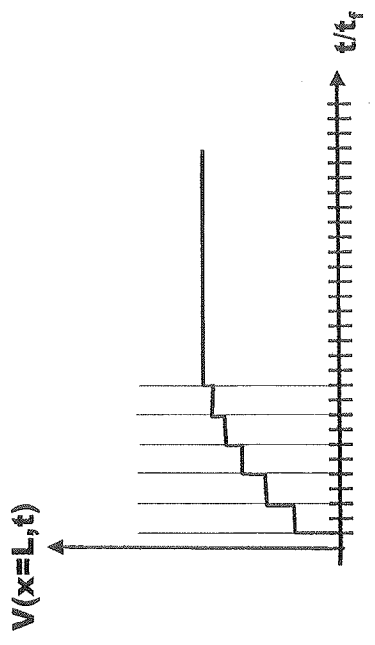
$$\Gamma_s = \frac{Z_{tr} - Z_0}{Z_{tr} + Z_0} \quad V(x=0, 0 < t < 2t_f) = V_{dd} \frac{Z_0}{R_{tr} + Z_0}$$

### Reflection Diagram



### Review: Lossless Transmission Line Analysis

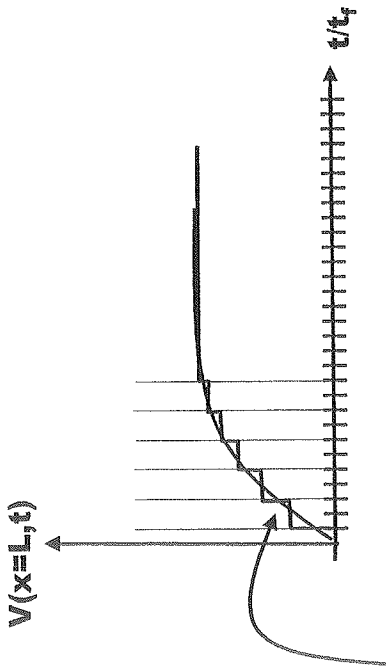
Example:  $R_{tr} \gg Z_0$  and  $Z_L = \text{inf}$





**Review: Lossless Transmission Line Analysis**

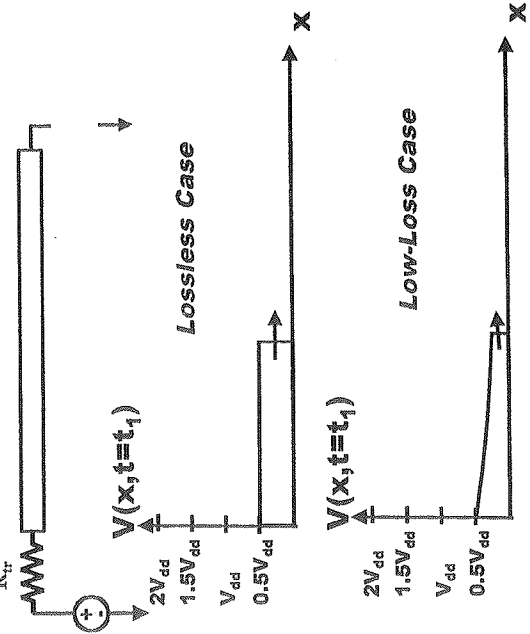
Example:  $R_{tr} \gg Z_0$  and  $Z_L = \text{inf}$



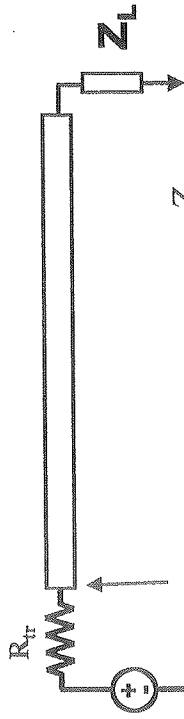
If  $R_{tr}$  is large enough starts to approach  $R_{tr}C$  curve!!

**Review: Low Loss Transmission Line Analysis**

Example:  $R_{tr} = Z_0$  and  $Z_L = \text{inf}$



**Review: Low Loss Transmission Line Analysis**



$$V(x=0, 0 < t < 2t_f) = V_{dd} \frac{Z_0}{R_{tr} + Z_0}$$



$$V(x, 0 < t < t_f) = V_{dd} \frac{Z_0}{R_{tr} + Z_0} e^{-\frac{rx}{2Z_0}}$$

**N-Wire Configuration**

$$\frac{\partial^2}{\partial x^2} \tilde{V} = r [C] \frac{\partial}{\partial t} \tilde{V} + [L][C] \frac{\partial^2}{\partial t^2} \tilde{V}$$

$$\tilde{V} = \begin{bmatrix} V_1 \\ \dots \\ V_n \end{bmatrix}$$

Assume all cross-sectional area are the same for each conductor

### Ideal Ground Plane

#### Approximation

$$\frac{\partial^2}{\partial x^2} \tilde{V} = r [C] \frac{\partial}{\partial t} \tilde{V} + [L] [C] \frac{\partial^2}{\partial t^2} \tilde{V}$$

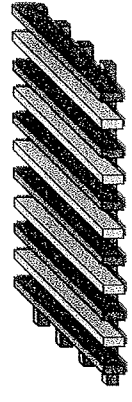
$$[I] \frac{1}{V^2} = [L] [C]$$

$$\frac{\partial^2}{\partial x^2} \tilde{V} = r [C] \frac{\partial}{\partial t} \tilde{V} + \frac{1}{V^2} \frac{\partial^2}{\partial t^2} \tilde{V}$$

eigenvectors of [C] decouples solution!

Orthogonal Lines makes decoupling difficult!

$$\frac{\partial^2}{\partial x^2} \tilde{V} = r [C] \frac{\partial}{\partial t} \tilde{V} + [L] [C] \frac{\partial^2}{\partial t^2} \tilde{V}$$

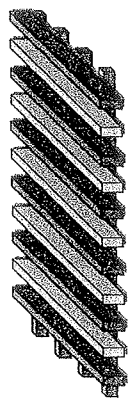


Except for the 2 line case-- In general this will not decouple!

### Inductance Approximation

However, could approximate with ...

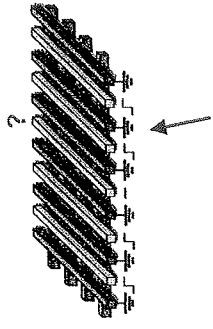
$$[L_{\text{with orthogonal lines}}]^{-1} \approx [C_{\text{remove orthogonal}}]^{-1} \frac{1}{V^2}$$



### Diagonalized Capacitance Matrix Approximation

$$\frac{\partial^2}{\partial x^2} \tilde{V} = r c \frac{\partial}{\partial t} \tilde{V} + [L] c \frac{\partial^2}{\partial t^2} \tilde{V}$$

Now eigenvectors of L matrix decouples lines AND single line solutions can be used!



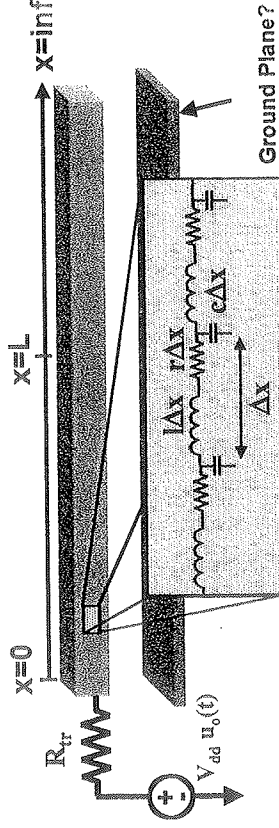
All identical and all aggressor switching simultaneously!

# Compact Models for Transient Voltage

## Distributed RLC Models

- ~~N-Line Solution~~
- 1-Line Solution
- 2-Line Example

Where to start?



$$\frac{\partial^2}{\partial x^2} V(x,t) = rc \frac{\partial}{\partial t} V(x,t) + lc \frac{\partial^2}{\partial t^2} V(x,t)$$

## Alternate Expansion

"Distributed RC"

$$V(x,s) = \frac{K_0}{s} + \frac{K_1}{(s-\delta_1)} + \frac{K_2}{(s-\delta_2)} + \dots + \frac{K_n}{(s-\delta_n)}$$

"Distributed RLC"

$$V(x,s) = \frac{e^{-x\sqrt{lc}\sqrt{s^2-\sigma^2}}}{\sqrt{s^2-\sigma^2}} \left( 1 + \frac{\sigma K_1}{(s+\sqrt{s^2-\sigma^2})} + \frac{\sigma^2 K_2}{(s+\sqrt{s^2-\sigma^2})^2} + \dots + \frac{\sigma^n K_n}{(s+\sqrt{s^2-\sigma^2})^n} \right)$$

## Inverse Laplace Transform

"Distributed RC"

$$\frac{K_n}{(s-\delta_n)} \rightarrow K_n e^{-\delta_n t}$$

"Distributed RLC"

$$\frac{e^{-x\sqrt{lc}\sqrt{s^2-\sigma^2}}}{\sqrt{s^2-\sigma^2}} \rightarrow \frac{\sigma^n}{\sqrt{s^2-\sigma^2} (s+\sqrt{s^2-\sigma^2})^n} \rightarrow \left( \frac{t-x\sqrt{lc}}{t+x\sqrt{lc}} \right)^n I_n \left[ \sigma \sqrt{t^2-x^2lc} \right] u_0(t-x\sqrt{lc})$$

Modified Bessel Function

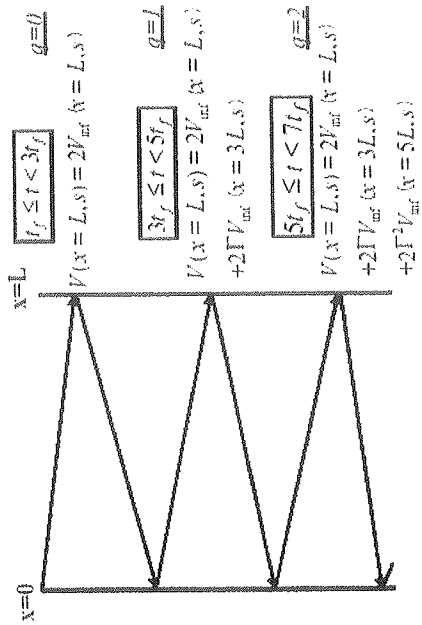
# Infinite Line Solution

**"Distributed RLC"**

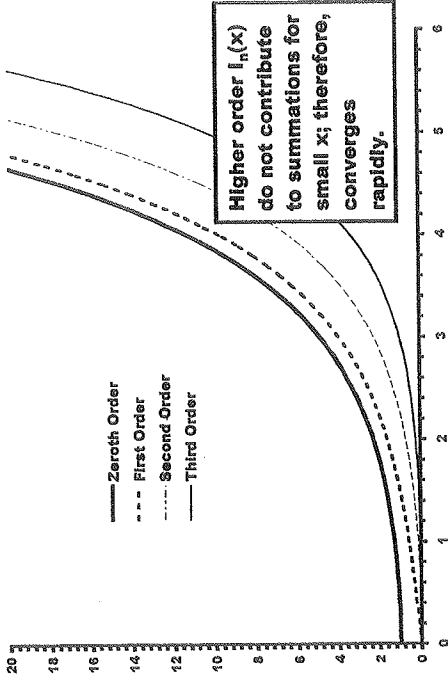
$$V_{inf}(x,t) = V_{df} \left[ \frac{Z_0}{R_s + Z_0} e^{\frac{R_s}{2L} t_0} \left[ \frac{R}{2L} \sqrt{t^2 - (x\sqrt{LC})^2} \right] + \frac{1}{2} \sum_{k=1}^{\infty} \left( \frac{t - x\sqrt{LC}}{t + x\sqrt{LC}} \right)^{\frac{1}{2k}} e^{\frac{R_s}{2L} I_k} \left[ \frac{R}{2L} \sqrt{t^2 - (x\sqrt{LC})^2} \right] \left( 4 - \Gamma^{k+1} (\Gamma + 1)^2 \right) \right] u \left[ t - x\sqrt{LC} \right]$$

Jeff Davis, Azad Naeemi, and James Meindl, "Chapter 4: Transient Models for RC and RLC Interconnects," in *Interconnect Technology and Design for Gigascale Integration*, 2003.

# Finite Line Solution



# Modified Bessel Functions



# Finite Line Solution

Infinite Line First Reflection

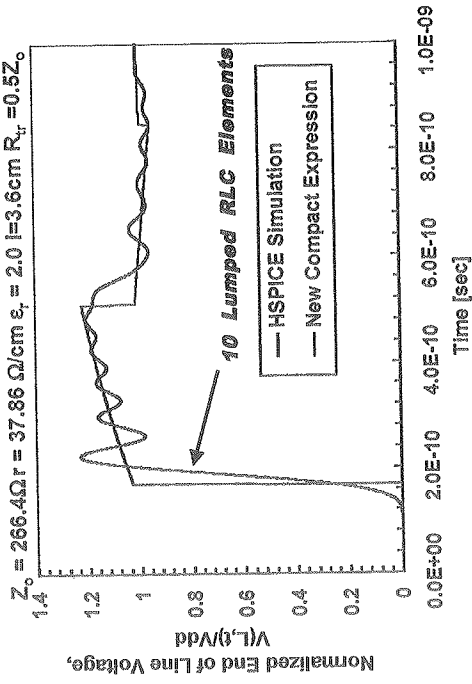
$$V_{FN}(\ell, t) = 2V_{gen}(\ell, t, m=0) + 2e^{-\frac{R_s}{2L} t} \sum_{n=1}^{\infty} \sum_{j=0}^n \frac{n(n-1+j)!}{i!j!(n-i)!} (-1)^i \Gamma^{n-i} V_{gen}(x = (2n+1)\ell, t, m = i+j)$$

Where  $V_{gen}$  is:

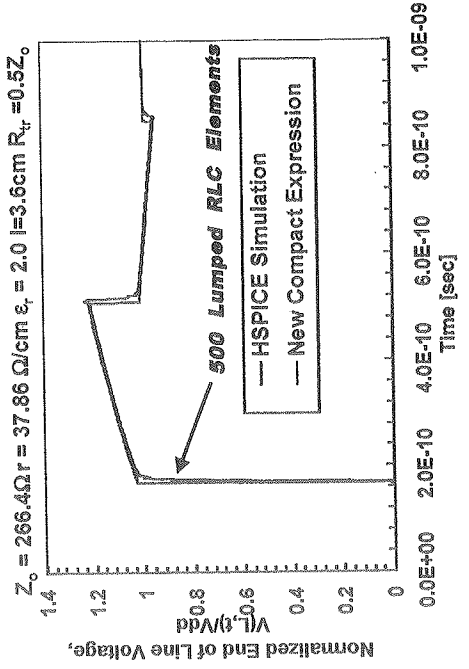
$$V_{gen}(x, t, m) = V_{df} \left[ \frac{Z_0}{R_s + Z_0} \left( \frac{t - x\sqrt{LC}}{t + x\sqrt{LC}} \right)^{\frac{m}{2}} e^{\frac{R_s}{2L} I_0} \left[ \frac{R}{2L} \sqrt{t^2 - (x\sqrt{LC})^2} \right] + \frac{1}{2} \sum_{k=1}^{\infty} \left( \frac{t - x\sqrt{LC}}{t + x\sqrt{LC}} \right)^{\frac{1}{2}(k+m)} e^{\frac{R_s}{2L} I_{k+m}} \left[ \frac{R}{2L} \sqrt{t^2 - (x\sqrt{LC})^2} \right] \left( 4 - \Gamma^{k+1} (\Gamma + 1)^2 \right) \right] u \left[ t - x\sqrt{LC} \right]$$

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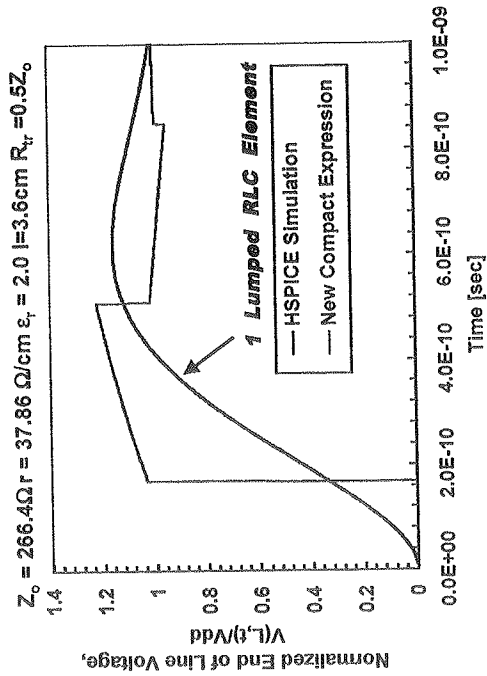
# HSPICE Comparison



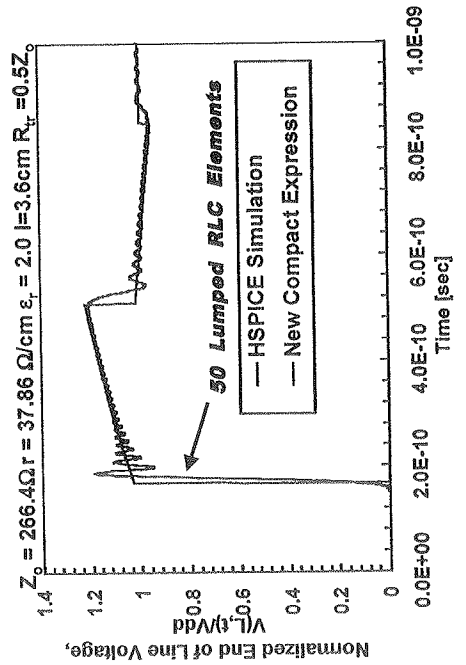
# HSPICE Comparison



# HSPICE Comparison

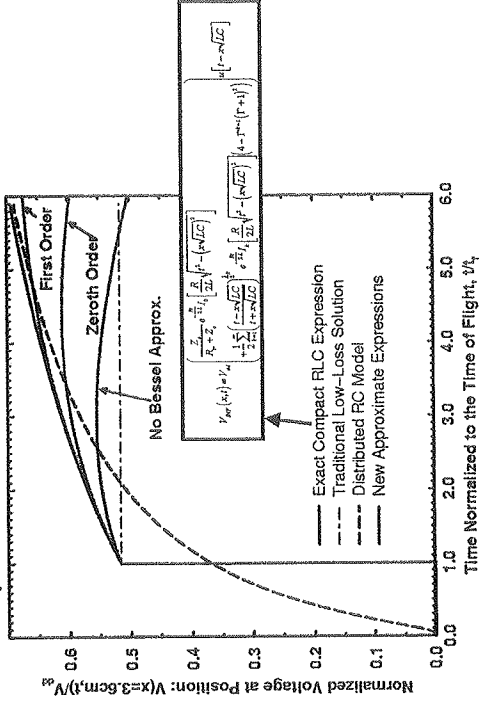


# HSPICE Comparison

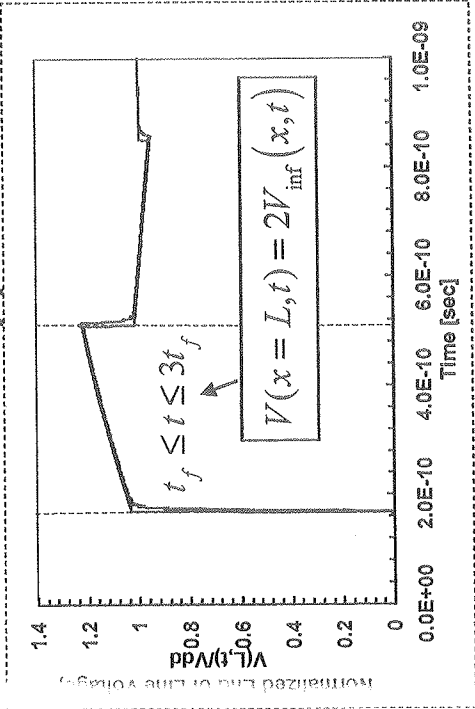


# Series Convergence Example

$Z_0 = 266.4 \Omega$ ,  $r = 37.86 \Omega/\text{cm}$ ,  $x = 3.6 \text{ cm}$ ,  $R_L = 133.2 \Omega$



# First Reflection Approximation



# First Reflection Approximation

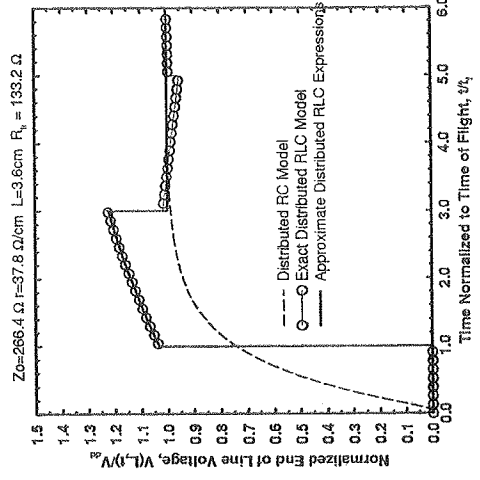
$$(1 > \tilde{t} > 3)$$

$$\tilde{t} = \frac{t}{x\sqrt{LC}}$$

$$V(t) = V_{DD} \left[ \frac{Z_0 - \tilde{t}}{R_s + Z_0} I_0 \left[ \frac{R}{2Z_0} \sqrt{\tilde{t}^2 - 1} \right] + \frac{1}{2} \left( (1 - \tilde{t}) \frac{R}{4Z_0} (4 - (1 + \Gamma)^2) - 4(1 - e^{-\frac{R}{4Z_0} \tilde{t}(\tilde{t} - 1)}) + \frac{R}{\Gamma} \tilde{t}(\tilde{t} - 1) + \frac{(1 + \Gamma)^2}{\Gamma} (1 - e^{-\frac{R}{4Z_0} \tilde{t}(\tilde{t} - 1)}) \right) \right]$$

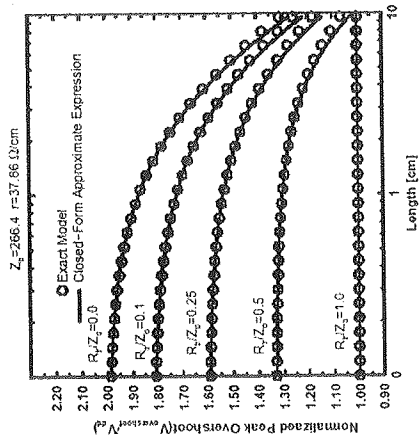
<b>max 5% error @ <math>3t_f</math>, as long as</b>	$R < (3/\sqrt{8})Z_0 \approx Z_0$
<b>max 10% error @ <math>3t_f</math>, as long as</b>	$R < \sqrt{2}Z_0 \approx 1.4Z_0$

# 1st Reflection Approximation

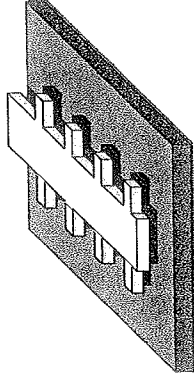


# Simplified Overshoot Validation

$$\frac{V_{overshoot}}{V_{dd}} = \max\left(1, \frac{V_{IR\_approx}(L, t = 3L\sqrt{lc})}{V_{dd}}\right)$$



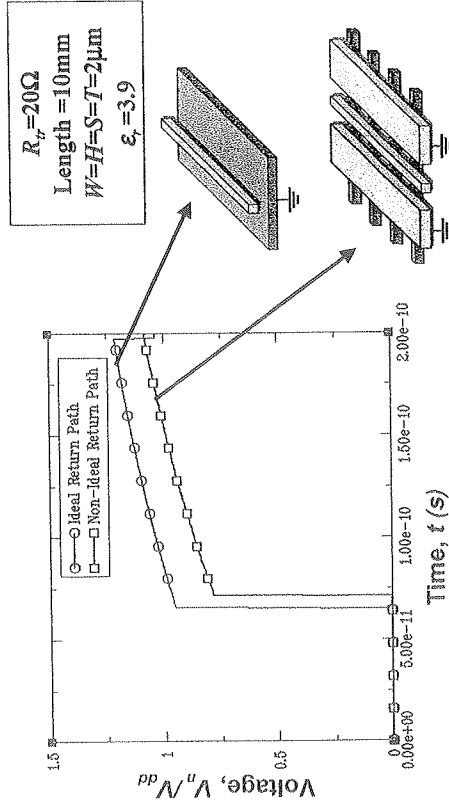
# Periodic Structures Microwave



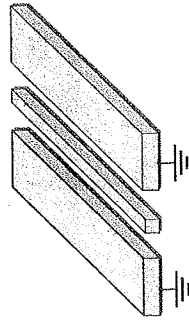
For large wavelengths, it behaves like a smooth transmission line but with a lower speed of wave:

$$v = \frac{1}{\sqrt{lc + \frac{C_0}{d}}} < \frac{c_0}{\sqrt{\epsilon_r}}$$

# Time of Flight Variation



# Single Line Structure

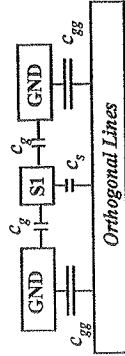
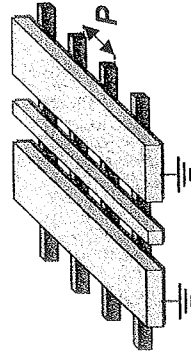


Ideal transmission line:

$$c_0 = \frac{1}{\epsilon_r \sqrt{lc}}$$

Non-ideal return path:

• For F=10GHz,  $\lambda = 1.5\text{cm} \gg P$



# Compact Models for Transient Voltage

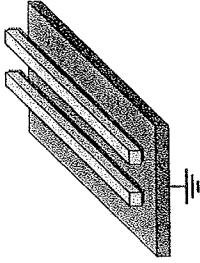
## Distributed RLC Models

- ~~N-Line Solution~~
- ~~1-Line Solution~~
- 2,3,&5-Line Example



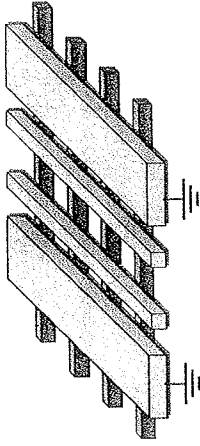
# Impact of Return Path on Crosstalk

Ideal Return Path



Interconnects with a nearby ground plane

Non-Ideal Return Path



On-chip interconnects over orthogonal lines

## 1&3 RLC Lines Over a Ground Plane

- ~~Single RLC Line~~

$$\frac{\partial^2}{\partial x^2} V(x,t) = rc \frac{\partial}{\partial t} V(x,t) + \frac{1}{v^2} \frac{\partial^2}{\partial t^2} V(x,t)$$

Active Victim Active

- 3 Coupled RLC Lines

$V_{sum} = V_{fin}(x,t, c = c_g, l = \frac{1}{c_g v^2})$	$V_{victim} = \frac{1}{3} V_{sum} - \frac{2}{3} V_{dif}$
$V_{dif} = V_{fin}(x,t, c = c_g + 3c_m, l = \frac{1}{(c_g + 3c_m)v^2})$	$V_{Active} = \frac{1}{3} V_{sum} + \frac{1}{3} V_{dif}$

## 5-Conductor RLC Line

$$\frac{\partial^2}{\partial x^2} V(x,t) = r[C] \frac{\partial}{\partial t} V(x,t) + \frac{1}{v^2} \frac{\partial^2}{\partial t^2} V(x,t)$$

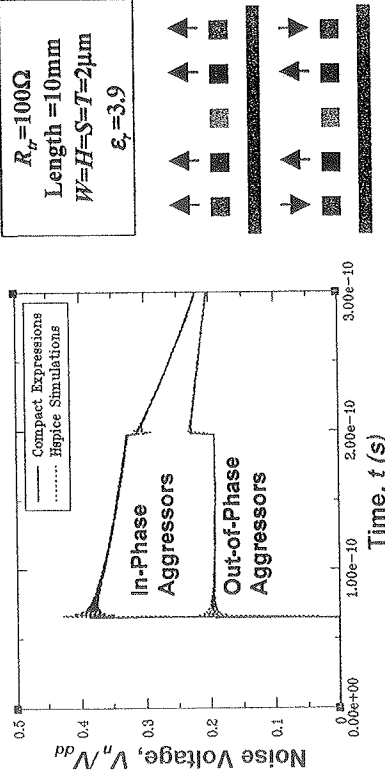
Far Near Victim Near Far

$V_{sum} = V_{fin}(x,t, c = c_g, l = \frac{1}{c_g v^2})$	$V_{victim} = 0.2V_{sum} - 0.32V_{dif1} + 0.124V_{dif2}$
$V_{dif1} = V_{fin}(x,t, c = c_g + \frac{5+\sqrt{5}}{2}c_m, l = \frac{1}{c_g v^2})$	$V_{near} = 0.2V_{sum} - 0.262V_{dif1} + 0.04V_{dif2}$
$V_{dif2} = V_{fin}(x,t, c = c_g + \frac{5-\sqrt{5}}{2}c_m, l = \frac{1}{c_g v^2})$	$V_{far} = 0.2V_{sum} - 0.1V_{dif1} + 0.1V_{dif2}$

With ground plane, all modes travel @ the speed of light!

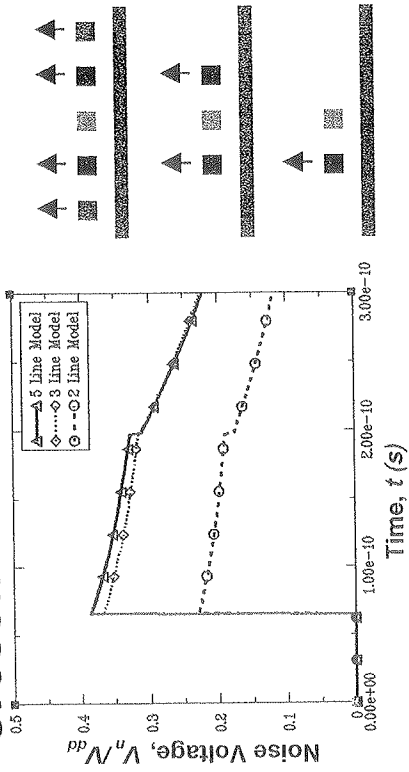


## HSPICE Verification



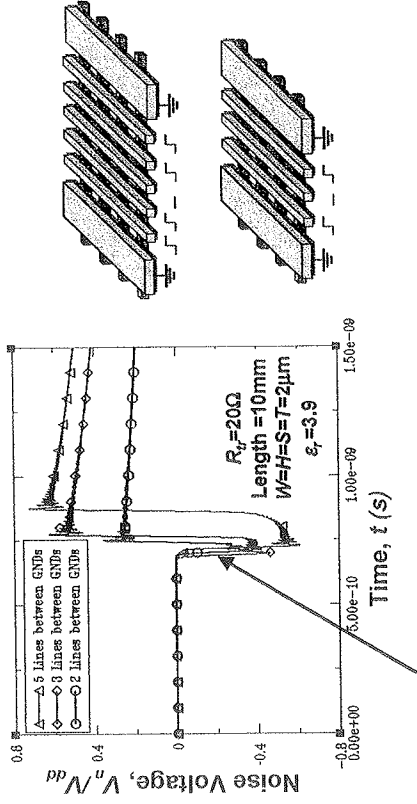
**The worst case crosstalk is when all aggressors switch in phase!!**

## Crosstalk With Ground Plane



**WITH GROUND PLANE far aggressor have smaller IMPACT!**

## Crosstalk With Orthogonal Lines

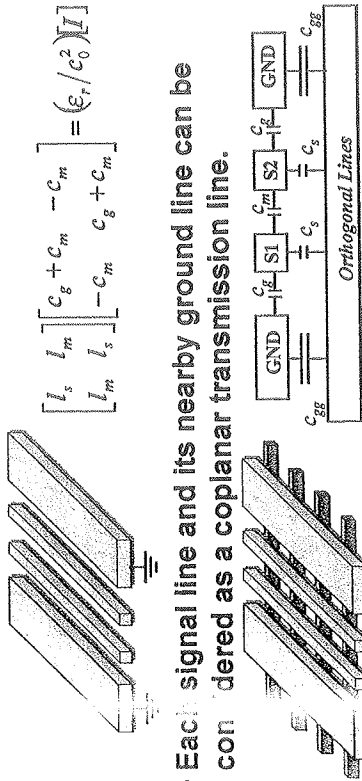


## Examples of Using Compact Interconnect Models

- Coplanar Optimization\*\*
- Maximum Bit-Rate Calculation
- Repeaters to Reduce Inductive Crosstalk

\*\*Azad Naeemi, Jeff Davis, and Jim Meindl, "Compact physical models for multilevel interconnect crosstalk in a Gigascale SoC", Proceedings of the SOC Conference, pp. 199-202, 2003.

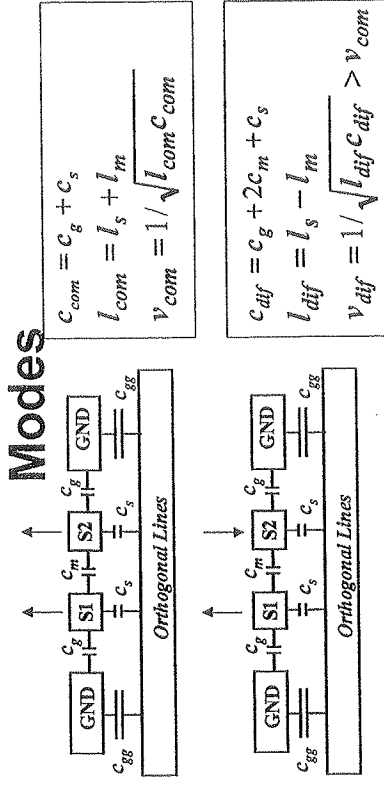
## Two Line Case



$$\begin{bmatrix} l_s & l_m \\ l_m & l_s \end{bmatrix} \begin{bmatrix} c_g + c_m & -c_m \\ -c_m & c_g + c_m \end{bmatrix} = (\epsilon_r / c_0^2) [I]$$

- Each signal line and its nearby ground line can be considered as a coplanar transmission line.
- Inductance values are not affected by orthogonal lines.
- Orthogonal lines just increase the capacitance.

## Common and Differential Modes

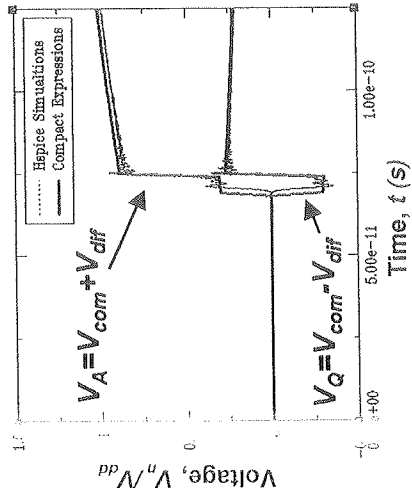


$$\begin{aligned} C_{com} &= C_g + C_s \\ l_{com} &= l_s + l_m \\ v_{com} &= 1 / \sqrt{l_{com} C_{com}} \end{aligned}$$

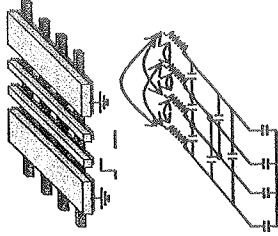
$$\begin{aligned} C_{dif} &= C_g + 2C_m + C_s \\ l_{dif} &= l_s - l_m \\ v_{dif} &= 1 / \sqrt{l_{dif} C_{dif}} > v_{com} \end{aligned}$$

Differential and common modes can be solved by the single RLC line model.

## HSPICE Comparison

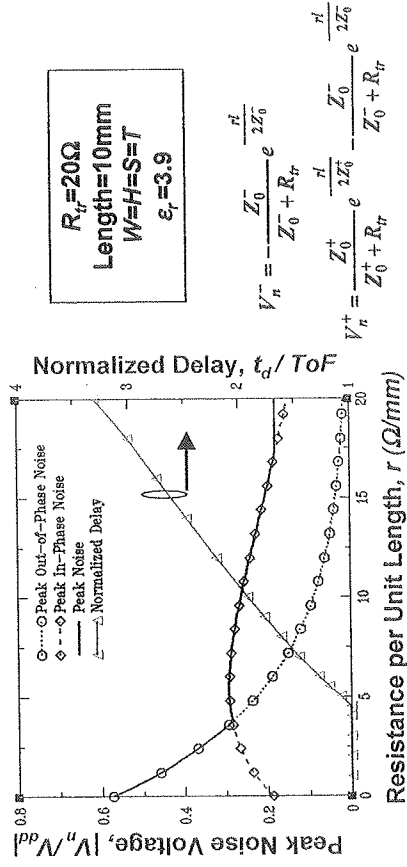


$R_{tr} = 20\Omega$   
Length=10mm  
 $W=H=S=T$   
 $\epsilon_r = 3.9$



An out-of-phase noise due to different speeds

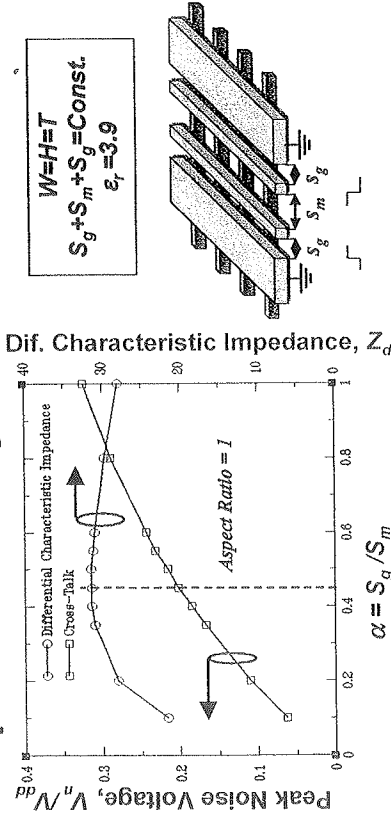
## Noise, Delay, and Resistance



$R_{tr} = 20\Omega$   
Length=10mm  
 $W=H=S=T$   
 $\epsilon_r = 3.9$

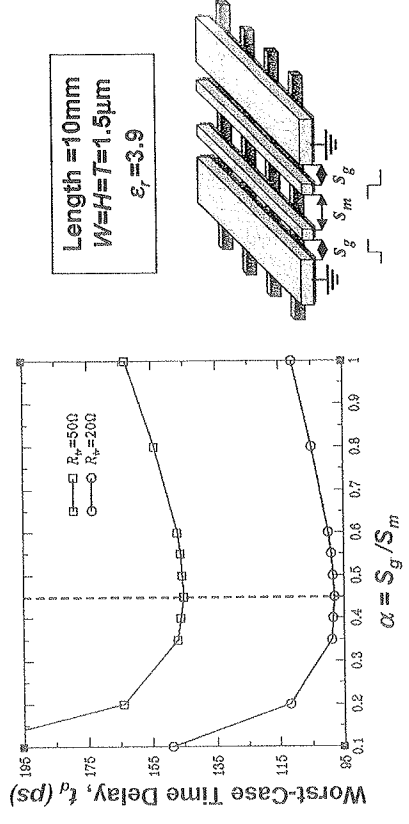
$$\begin{aligned} V_n^+ &= \frac{Z_0^-}{Z_0^+ + R_{tr}} e^{-\frac{r}{2Z_0^+}} \\ V_n^- &= \frac{Z_0^+}{Z_0^- + R_{tr}} e^{-\frac{r}{2Z_0^-}} \end{aligned}$$

## Optimize Delay and Noise



- Characteristic impedance is maximum at  $S_g/S_m=0.45$ .
- 38% crosstalk reduction by changing  $S_g/S_m$  from 1 to 0.45.

## Optimize Noise & Delay



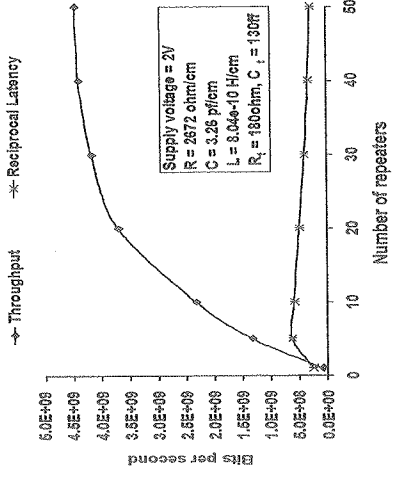
- 10% reduction in delay by changing  $S_g/S_m$  from 1 to 0.45.

## Examples of Using Compact Interconnect Models

- Coplanar Optimization
- Maximum Bit-Rate Calculation\*\*
- Repeaters to Reduce Inductive Crosstalk

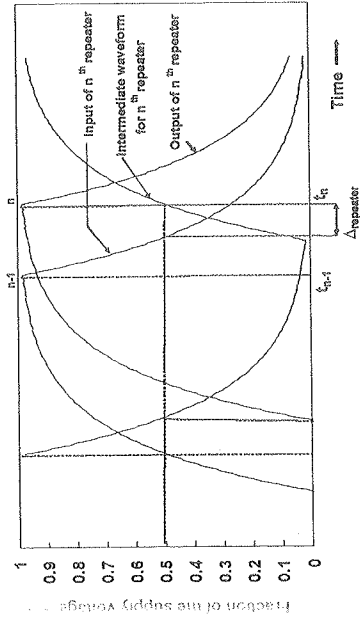
\*\*V. Deodhar and J. Davis, "Voltage Scaling and Repeater Insertion for High-Throughput Low-Power Interconnect Networks", Proceedings of the 2003 ISCAS, Bangkok, Thailand, pp. 349-353, June 2003.

## Maximum Bit-Rate vs. Reciprocal Latency



## Maximum Bit-Rate Criteria

When can I switch the input and still obtain a 90% swing on last inverter?



## Voltages on Repeaters

$$t_n = \sigma_{RCseg} \ln \left( \frac{k_1}{1-v_n} \right) + (n-1) \sigma_{RCseg} \ln \left( \frac{k_1}{1-0.5} \right) + n \Delta_{repeater}$$

$$t_{n-1} = \sigma_{RCseg} \ln \left( \frac{k_1}{1-v_{n-1}} \right) + (n-2) \sigma_{RCseg} \ln \left( \frac{k_1}{1-0.5} \right) + (n-1) \Delta_{repeater}$$

$$v_{n-1} k_1 e^{-(t_n - t_{n-1} - \Delta_{repeater}) / \sigma_{RCseg}} = 0.5$$

$$v_{n-1} k_1 e^{-\left( \ln 2 k_1 + \ln \left( \frac{1-v_{n-1}}{1-v_n} \right) \right)} = 0.5$$

$$v_{n-1} = \frac{1}{2 - v_n}$$

## Compact Bit-Rate Expressions

$$v = 1 - \sum_{k=1}^{\infty} k_1 e^{-k/\sigma_k} \approx 1 - k_1 e^{-1/\sigma_1}$$

$$t_v = \sigma_{RCseg} \ln \left( \frac{k_1}{1-v} \right)$$

$$\Delta_{repeater} = 0.693 R_i C_i$$

$$\sigma_{RCseg} = R_i C_i + R_i C_{seg} + C_i R_{seg} + 0.4 R_{seg} C_{seg}$$

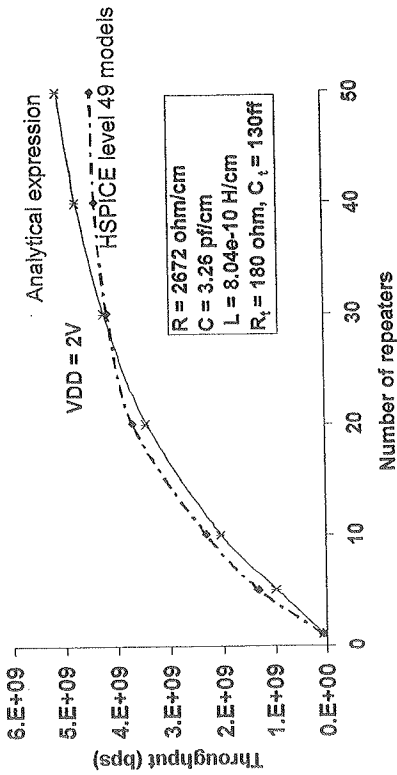
$$k_1 = 1.01 \left[ \frac{R_i C_{seg} + R_{seg} C_i + R_{seg} C_{seg}}{R_i C_{seg} + R_{seg} C_i + \frac{\pi}{4} R_{seg} C_{seg}} \right]$$

## Compact Maximum Bit-Rate Expression

$$PW_{min} = \sigma_{RCseg} \ln \left( \frac{k_1}{1-v_1} \right) + \Delta_{repeater}$$

$$T_{max} = \frac{1}{\sigma_{RCseg} \ln \left( \frac{k_1}{1-v_1} \right) + \Delta_{repeater}}$$

# HSPICE vs. Compact Model



# Throughput Saturation

$$\left[ \ln\left(\frac{k_1}{1-v_1}\right) + 0.693 \right] R_0 C_0 = \ln\left(\frac{k_1}{1-v_1}\right) \left( 0.4 \frac{rl}{n} \frac{cl}{n} + \frac{R_0}{h} \frac{cl}{n} + C_0 h \frac{rl}{n} \right)$$

$$T_{sat} \approx \frac{1}{2 \left[ \ln\left(\frac{1}{1-v_1}\right) + 0.693 \right] R_i C_i}$$

Saturation throughput is independent of interconnect parameters !

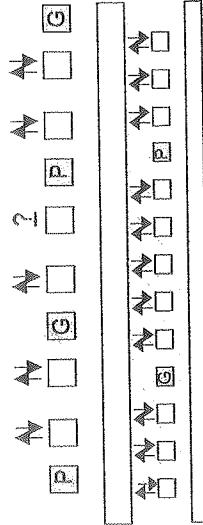
# Examples of Using Compact Interconnect Models

- Coplanar Optimization
- Maximum Bit-Rate Calculation
- Repeaters to Reduce Inductive Crosstalk\*\*



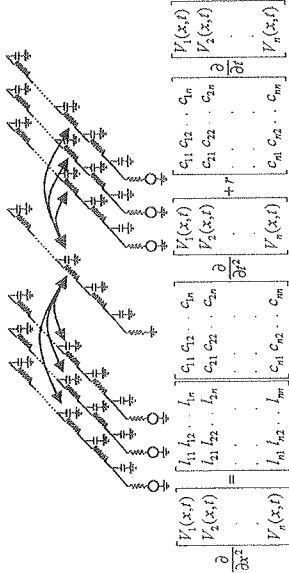
\*\*A. Naeemi, J.A. Davis, and J.D. Meindl, "Compact Physical Models for the Worst Case Crosstalk Induced by Near and Far Aggressors in a SOC," IEEE International ASIC/Soc Conference, Sept 2003, pp. 199-202.

# Apply Compact Model Here?



$$\frac{\partial}{\partial x^2} \begin{bmatrix} V_1(x,f) \\ V_2(x,f) \\ \vdots \\ V_n(x,f) \end{bmatrix} = \begin{bmatrix} l_{11} & l_{12} & \dots & l_{1n} \\ l_{21} & l_{22} & \dots & l_{2n} \\ \vdots & \vdots & \ddots & \vdots \\ l_{n1} & l_{n2} & \dots & l_{nn} \end{bmatrix} \begin{bmatrix} V_1(x,f) \\ V_2(x,f) \\ \vdots \\ V_n(x,f) \end{bmatrix} + \begin{bmatrix} c_{11} & c_{12} & \dots & c_{1n} \\ c_{21} & c_{22} & \dots & c_{2n} \\ \vdots & \vdots & \ddots & \vdots \\ c_{n1} & c_{n2} & \dots & c_{nn} \end{bmatrix} \begin{bmatrix} \frac{\partial}{\partial t} V_1(x,f) \\ \frac{\partial}{\partial t} V_2(x,f) \\ \vdots \\ \frac{\partial}{\partial t} V_n(x,f) \end{bmatrix}$$

# The simplification ..



- Mutual capacitances between the far lines and the victim line are negligible.
- For the worst-case scenario, far aggressors switch in-phase; mutual capacitances between far lines can be ignored, too.

$$\frac{\partial}{\partial x^2} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix} = \begin{bmatrix} l_{11} & l_{12} & \dots & l_{1n} \\ l_{21} & l_{22} & \dots & l_{2n} \\ \vdots & \vdots & \ddots & \vdots \\ l_{n1} & l_{n2} & \dots & l_{nn} \end{bmatrix} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix} + r \begin{bmatrix} c_{11} & c_{12} & \dots & c_{1n} \\ c_{21} & c_{22} & \dots & c_{2n} \\ \vdots & \vdots & \ddots & \vdots \\ c_{n1} & c_{n2} & \dots & c_{nn} \end{bmatrix} \frac{\partial}{\partial t} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix}$$

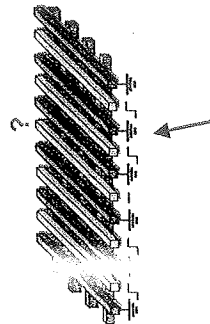
$$\frac{\partial}{\partial x^2} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix} = \begin{bmatrix} l_{11} & l_{12} & \dots & l_{1n} \\ l_{21} & l_{22} & \dots & l_{2n} \\ \vdots & \vdots & \ddots & \vdots \\ l_{n1} & l_{n2} & \dots & l_{nn} \end{bmatrix} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix} + rc \frac{\partial}{\partial t} \begin{bmatrix} V_1(x,t) \\ V_2(x,t) \\ \vdots \\ V_n(x,t) \end{bmatrix}$$

# The simplification

## Diagonalized Capacitance Matrix Approximation

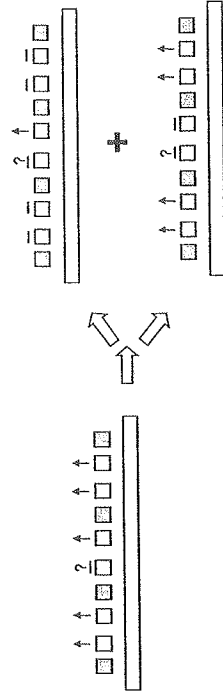
$$\frac{\partial^2}{\partial x^2} \tilde{V} = rc \frac{\partial}{\partial t} \tilde{V} + [L]c \frac{\partial^2}{\partial t^2} \tilde{V}$$

Now eigenvectors of  $L$  matrix decouples lines



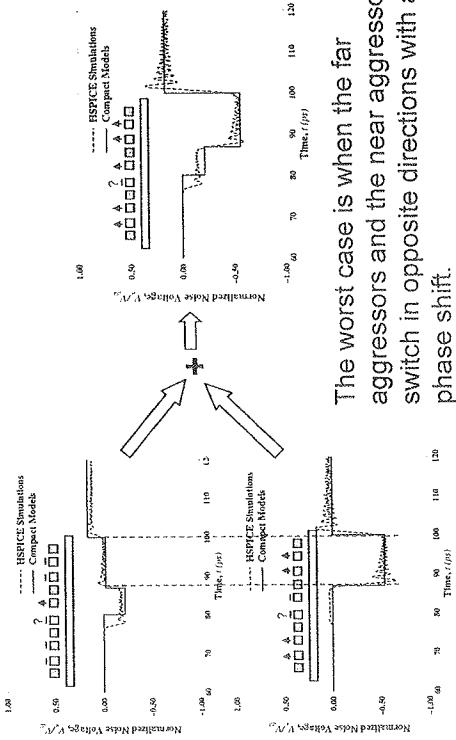
All identical and all aggressor switching simultaneously!

## Superposition



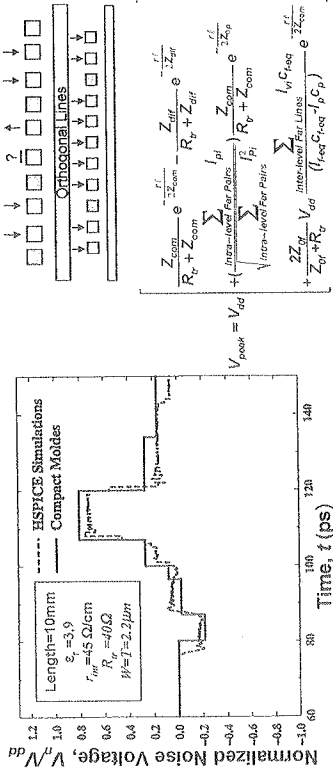
Using superposition theorem, total crosstalk caused by near and far aggressors can be calculated.

# Superposition

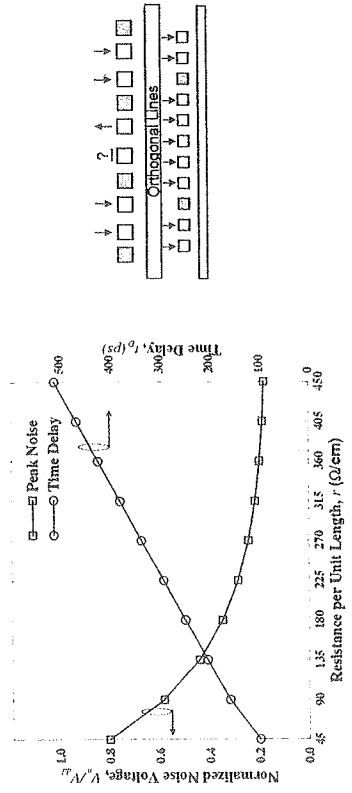


The worst case is when the far aggressors and the near aggressor switch in opposite directions with a phase shift.

# Worst-Case Crosstalk

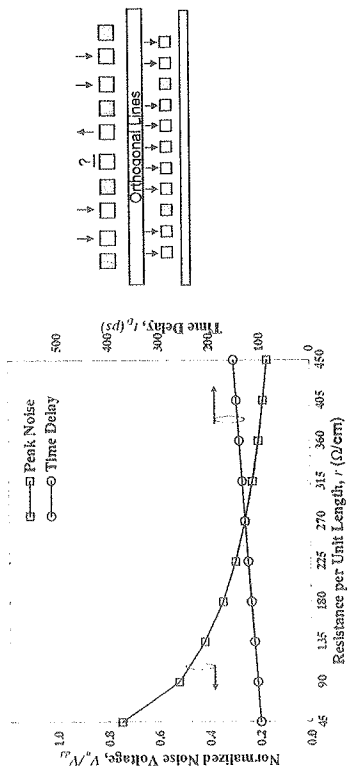


# Latency and Crosstalk Tradeoff



There is a trade-off between crosstalk and interconnect latency.

# Repeater Insertion



Repeater insertion is an effective way to lower crosstalk and increase wiring density with a small latency penalty.

## What have we learned?

### Compact Models For R,L, &C

- Basic empirical formulas for L&C

### Compact Distributed RC Models

- Single conductor problem can be used to model *regular* n-wire configurations
- Finite rise-time model increases accuracy of non-linear driver operation

## What have we learned?

### Compact Model Analysis Examples

- Coplanar global wire dimensions are optimized to reduce the delay and crosstalk by 10% and 38%
- Maximum bit rate can be much greater than reciprocal latency
- Use of single line solutions in complex configurations
- Repeater insertion is an effective way to lower inductive crosstalk

## What have we learned?

### Compact Distributed RLC Models

- Modified Bessel series solutions
- First reflection approximation for delay and crosstalk approximations
- Orthogonal ground lines slows time-of-flight and causes modal dispersion
- Orthogonal conductors cause far aggressors to have a larger impact on crosstalk



# Wave Pipelining using Repeaters for VLSI Global Interconnects

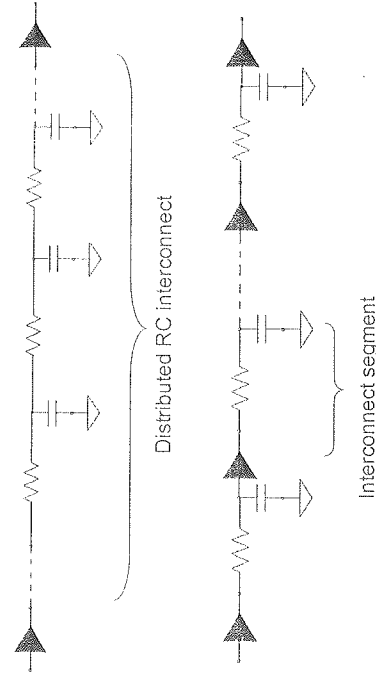
Vinita V. Deodhar

ECE 8823

Advanced VLSI Interconnect Design  
Instructor: Dr. Jeffrey A. Davis

March 15, 2005

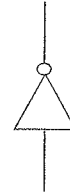
## Repeater Insertion



## Repeater Circuits

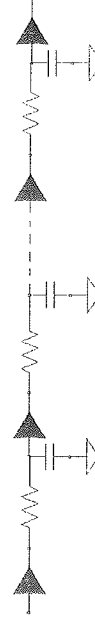


Inverting repeater



Non-inverting repeater

## Bakoglu Repeater Insertion



\*Optimal number of repeaters

$$n_{opt} = \sqrt{\frac{RC}{2.3R_0C_0}}$$

\*Optimal size of repeaters

$$h_{opt} = \sqrt{\frac{R_0C}{C_0R}}$$

\*H. Bakoglu and J. Meindl, IEEE Trans. Electron Devices, vol. ED-32, no. 5, pp. 903-909, May 1985.

## Propagation Delay

➤ For a single driver interconnect,  
 $T \propto (\text{Interconnect length})^2$

➤ For interconnect with repeaters,

$$T = 7.6 \sqrt{R_o C_o RC}$$

$T \propto$  Interconnect length

\*H. Bakoglu and J. Meindl, *IEEE Trans. Electron Devices*, vol. ED-32, no.5, pp. 903-909, May, 1985.

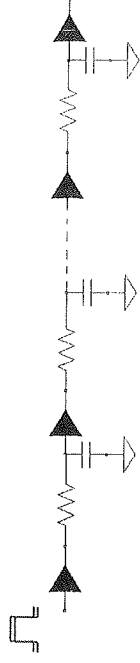
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## Data Propagation



$$\text{Bit-rate} = \frac{1}{\text{Communication latency}}$$

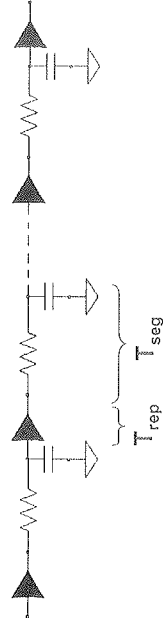
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## Concept of Wave Pipelining



$$\text{Segment Delay} \sim T_{\text{rep}} + T_{\text{seg}}$$

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## Data Propagation using Wave Pipelining



$$\text{Throughput Bit-rate} \approx \frac{1}{\text{Segment delay}}$$

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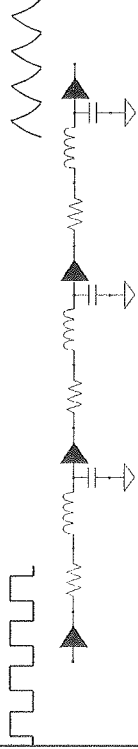
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## Calculating Throughput of Wave-Pipelined Interconnect in HSPICE

Requirements:

- Every data bit is captured at the output.
- The last segment reaches 90%  $V_{dd}$ .



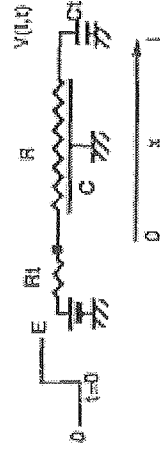
## HSPICE Analysis

Accurate but not efficient

- Tedious
- Time-consuming
- Trial and error

**Need for a simple analytical throughput model**

## Sakurai Interconnect Model



A model of an interconnection driven by a resistive voltage source and loaded with a capacitor

T. Sakurai, *IEEE Trans. Electron Devices*, vol. 40, no. 1, pp. 118-124, Jan. 1993.

## Voltage at the Far End

$$V = \frac{V(l,t)}{E} = 1 + \sum_{k=1}^{\infty} K_k e^{-\alpha_k l / RC} \approx 1 + K_1 e^{-\alpha_1 l / RC}$$

$$K_1 = -1.01 \frac{R_T + C_T + 1}{R_T + C_T + \pi/4}$$

$$\alpha_1 = \frac{1.04}{R_T C_T + R_T + C_T + (2/\pi)^2}$$

$$R_T = \frac{R_f}{R}$$

$$C_T = \frac{C_f}{C}$$

## Sakurai Delay Model for Interconnect Segment

$$t_b = \sigma_{RCseg} \ln \left( \frac{K_1}{1-v} \right)$$

$$\sigma_{RCseg} = R_l \dot{C}_l + R_l C_{seg} + C_l R_{seg} + 0.4 R_{seg} C_{seg}$$

$$K_1 = 1.01 \left[ \frac{R_l C_{seg} + R_{seg} C_l + R_{seg} C_{seg}}{R_l C_{seg} + R_{seg} C_l + \frac{\pi}{4} R_{seg} C_{seg}} \right]$$

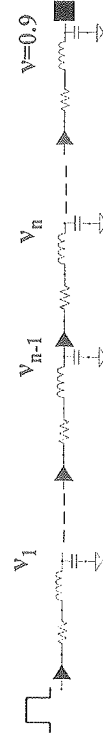
## Analytical Throughput Expression

Assumptions:

- The repeater consists of two coupled inverters.
- The inverter turns on at 50%  $V_{dd}$ .
- The last segment reaches 90%  $V_{dd}$ .

## Problem Definition

$v_n$  = Normalized maximum voltage swing on  $n^{\text{th}}$  segment



For  $v = 0.9$  on the last segment,  $v_1 = ??$

## Design Equations

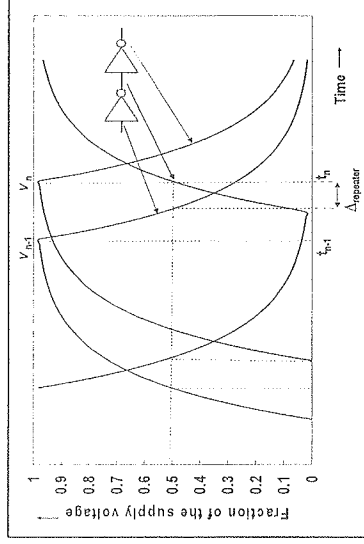
$$t_n = \sigma_{RCseg} \ln \left( \frac{K_1}{1-v_n} \right) + (n-1) \sigma_{RCseg} \ln \left( \frac{K_1}{1-0.5} \right) + n \Delta_{repeater}$$

$$t_{n-1} = \sigma_{RCseg} \ln \left( \frac{K_1}{1-v_{n-1}} \right) + (n-2) \sigma_{RCseg} \ln \left( \frac{K_1}{1-0.5} \right) + (n-1) \Delta_{repeater}$$

where

$$\Delta_{repeater} = 0.693 R_l C_l$$

## Repeater Waveforms



$$V_{n-1} K_1 e^{-(t_n - t_{n-1} - \Delta_{\text{repeater}}) / \sigma_{RC\text{seg}}} = 0.5$$

## Intermediate Equations

$$V_{n-1} K_1 e^{-\left(\ln(2K_1) + \ln\left(\frac{1-V_{n-1}}{1-V_n}\right)\right)} = 0.5$$

$$V_{n-1} K_1 e^{-\ln(2K_1) \left(\frac{1-V_{n-1}}{1-V_n}\right)} = 0.5$$

$$V_{n-1} K_1 \frac{1-V_n}{(2K_1)(1-V_{n-1})} = 0.5$$

$$\frac{(V_{n-1})(1-V_n)}{(1-V_{n-1})} = 1$$

## Recursive Relation

$$V_{n-1} = \frac{1}{2 - V_n}$$

By setting  $V_n$  for last segment to 0.9,  $V_1$  for the first segment can be recursively calculated.

These values are independent of all technology attributes of the interconnect circuit and are fundamental to multi-bit transmission on VLSI interconnects with repeaters.

## Table of Recursive Values

n #	$V_n$	n #	$V_n$	n #	$V_n$	n #	$V_n$	n #	$V_n$
1	0.983	11	0.980	21	0.974	31	0.966	41	0.947
2	0.983	12	0.979	22	0.974	32	0.964	42	0.944
3	0.982	13	0.979	23	0.973	33	0.963	43	0.941
4	0.982	14	0.978	24	0.972	34	0.962	44	0.937
5	0.982	15	0.978	25	0.971	35	0.960	45	0.933
6	0.981	16	0.977	26	0.971	36	0.958	46	0.929
7	0.981	17	0.977	27	0.970	37	0.957	47	0.923
8	0.981	18	0.976	28	0.969	38	0.955	48	0.916
9	0.980	19	0.976	29	0.968	39	0.952	49	0.909
10	0.980	20	0.975	30	0.967	40	0.950	50	0.900

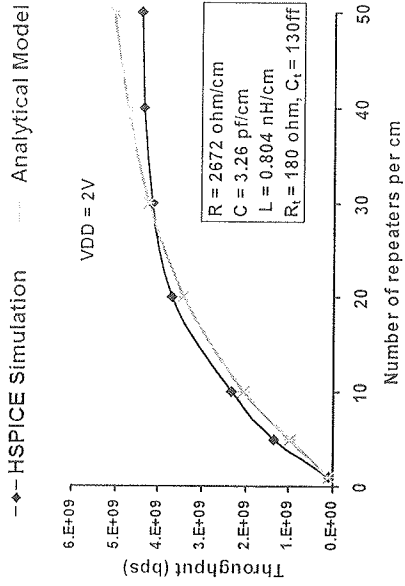
n # = repeater id in a chain of 50 repeaters

### Expressions for Pulsewidth and Throughput

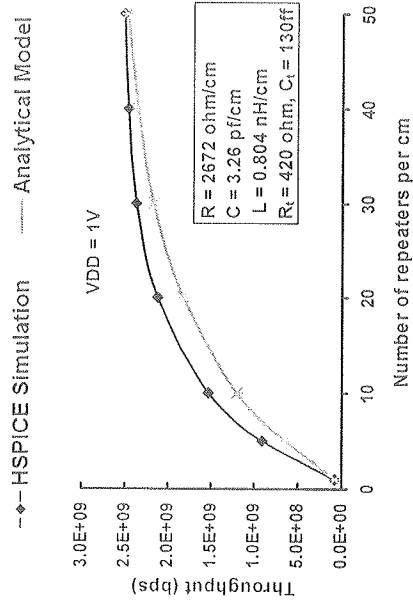
$$PW_{\min} = \sigma_{RC,seg} \ln \left( \frac{K_1}{1-V_1} \right) + \Delta_{repeater}$$

$$T_{\max} = \frac{1}{\underbrace{\sigma_{RC,seg} \ln \left( \frac{K_1}{1-V_1} \right)}_{\text{Delay of a repeated wire segment}} + \underbrace{\Delta_{repeater}}_{\text{Internal delay of a repeater}}}$$

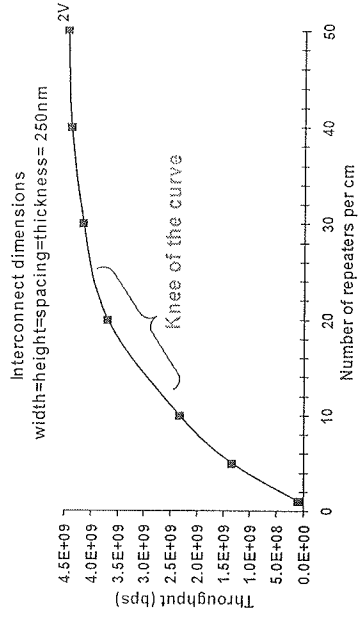
### 180 nm HSPICE Verification: 2V



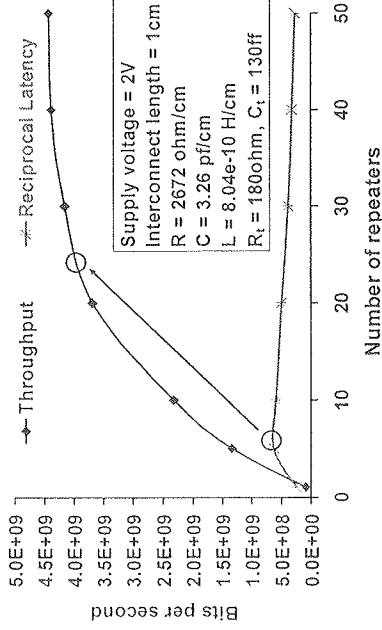
### 180 nm HSPICE Verification: 1V



### Operational Region



## Throughput-Centric vs. Latency-Centric Approach



## Physical Understanding using Analytical Throughput Expression

- Impact of circuit parameters on throughput
  - Interconnect length
  - Repeater scaling factor
- Effect of scaling on throughput
  - Constant field scaling
  - Global wire scaling

## Throughput Model

$$T_{\max} = \frac{1}{\sigma_{RC, \text{seg}} \ln \left( \frac{K_1}{1 - v_1} \right) + \Delta_{\text{repeater}}}$$



$$T_{\max} = \frac{1}{\left( \frac{R_0 c l}{h n} + C_0 h \frac{r l}{n} + R_0 C_0 + 0.4 \frac{r l c l}{n n} \right) \ln \left( \frac{K_1}{1 - v_1} \right) + 0.693 R_0 C_0}$$

## Wire length dependence of throughput

$$T_{\max} = \frac{1}{R_l C_l + R_l \frac{c}{(n/l)} + C_l \frac{r}{(n/l)} + 0.4 \frac{r c}{(n/l)^2} \ln \left( \frac{K_1}{1 - v_1} \right) + 0.693 R_l C_l}$$

└ CONSTANT

Throughput does not vary with number of repeaters or interconnect length alone but it is a function of their ratio